# Product End-of-Life Disassembly Instructions

## Product Category: Monitors and Displays

### Marketing Name / Model
[List multiple models if applicable.]

- **HP 25mx Display**

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm I/F Board<em>1, SPS board</em>1, Control Board*1, LENS Board</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel*1</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensors (Containing PCB/PCT)</td>
<td>0</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>C605 in SPS Board</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>HDMI cable<em>1, Power cord</em>1</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers

Components, parts and materials containing radioactive substances 0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>2</td>
</tr>
<tr>
<td>Hexagon Screw Driver</td>
<td>1</td>
</tr>
<tr>
<td>Flathead screwdriver</td>
<td>1</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Use tool to release screws on monitor, then separate the Stand from monitor head.
2. Use tool to release screws on monitor, then use tool to separate rear cover from monitor head through tear down slot.
3. Disassemble the lamp wire, LVDS FFC*2 and ctrl-BD FFC from connector, tear the tape*2 from chassis, separate Assy- chassis from monitor head by hand.
4. Disassemble the lamp wire from panel, and disassemble ctrl-BD from MF by hand.
5. Use tool to release screws*9 on MF, then separate the MF from panel.
6. Use tool to release Hexagon screw*2 from SHD, then release screws*7 on the power board and interface board, then disassemble power-BD and interface-BD from the chassis by hand.
7. Disassemble the LVDS*2 by hand.
8. Release Column & base by hand.
9. Use tool to release screw*3 from Column.
10.
11.
12.
13.
14.
15.
16.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Use tool to release screws on monitor, then separate the Stand from monitor head

2. Use tool to release screws on monitor, then use tool to separate rear cover from monitor head through tear down slot.
3. Disassemble the lamp wire, LVDS FFC*2 and ctrl-BD FFC from connector, separate Assy- chassis from monitor head by hand.

4. Disassemble the lamp wire from panel, and disassemble ctrl-BD and LED BD from MF by hand.
5. Use tool to release screws*8 on MF, then separate the MF from panel.

6. Use tool to release screws*7 on the power board and interface board, then disassemble power-BD and interface-BD from the chassis by hand.
7. Disassemble the LVDS*1 by hand.

8. Separate foot rubbers by hands or tools.
9. Release the screws from the base bracket, then disassemble the base plastic cover, swivel ring, and base bracket.

10. Use tool to release screws and separate VESA from column.

11. Use tool to separate vesa cover and vesa bracket.
12. Use tool to release screws and separate pivot cover.

13. Use tool to release screws and separate tilt cover.
14. Use tool to separate column front cover and engine cover.

15. Use tool to release screws and separate column rear cover.